



Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		PMP10624	Any	Printed Circuit Board	
C1, C2, C5	3	0.22uF	C1608X7R1H224K080AB	TDK	CAP, CERM, 0.22uF, 50V, +/-10%, X7R, 0603	0603
C3, C10	2	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C4, C15, C19, C20	4	0.1uF	06033C104JAT2A	AVX	CAP, CERM, 0.1 µF, 25 V, +/- 5%, X7R, 0603	0603
C6	1	1uF	GRM188R71C105KA12D	MuRata	CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603	0603
C7	1	10uF	EMK212BB7106MG-T	Taiyo Yuden	CAP, CERM, 10 µF, 16 V, +/- 20%, X7R, 0805	0805
C8, C16	2	0.22uF	C1608X7R1H224K080AB	TDK	CAP, CERM, 0.22 μF, 50 V, +/- 10%, X7R, 0603	0603
C9, R7	2	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
C11	1	0.047uF	GRM188R71H473KA61D	MuRata	CAP, CERM, 0.047 µF, 50 V, +/- 10%, X7R, 0603	0603
C13	1	0.022uF	GRM188R71H223KA01D	MuRata	CAP, CERM, 0.022 µF, 50 V, +/- 10%, X7R, 0603	0603
C14	1	220pF	GRM1885C1H221JA01D	MuRata	CAP, CERM, 220 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C17	1	47pF	GRM1885C1H470JA01D	MuRata	CAP, CERM, 47 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
Cin1, Co1	2	68uF	EEE-FK1J680UP	Panasonic	CAP, AL, 68 µF, 63 V, +/- 20%, 0.65 ohm, SMD	SMT Radial F
Cin2, Cin3, Cin4, Co2, Co3, Co4	6	4.7uF	GRM31CR71H475KA12L	MuRata	CAP, CERM, 4.7 μF, 50 V, +/- 10%, X7R, 1206	1206
D1	1	30V	BAT54HT1G	ON Semiconductor	Diode, Schottky, 30V, 0.2A, SOD-323	SOD-323
D2, D3	2	100V	BAS516,115	NXP Semiconductor	Diode, Switching, 100V, 0.25A, SOD-523	SOD-523
H1, H2, H3, H4	4	1001	NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5. H6. H7. H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
J1, J2, J3, J4	4		575-4	Keystone	Standard Banana Jack, Uninsulated, 5.5mm	Keystone 575-4
J5	1		PEC05DAAN	Sullins Connector Solutions	Header, 100mil, 5x2, Tin, TH	Header, 5x2, 100mil, Tin
J6	1		PEC02SAAN	Sullins Connector Solutions	Header, 100mil, 2x1, Tin, TH	Header, 2 PIN,
J7	1		PEC04DAAN	Sullins Connector Solutions	Header, 100mil, 4x2, Tin, TH	100mil, Tin Header, 4x2, 100mil,
1.4	4	CONT	IIII DAGAODZEDCDOMOA	Viehev Dele	Industry Chickled Developed Iron C.O. et J. O.A. 0.0000 above CMD	Tin IHLP-4040DZ
L1	1 2	6.8uH	IHLP4040DZER6R8M01	Vishay-Dale	Inductor, Shielded, Powdered Iron, 6.8 µH, 8 A, 0.0233 ohm, SMD	PG-TSDSON-8
Q1, Q3 Q2, Q4		30V 60V	BSZ0902NS BSZ042N06NS	Infineon Technologies	MOSFET, N-CH, 30 V, 40 A, PG-TSDSON-8 MOSFET, N-CH, 60 V, 17 A, PG-TSDSON-8	PG-TSDSON-8
	2			Infineon Technologies		
Q5 R1	1 1	60V 130k	2N7002-7-F CRCW0603130KJNEA	Diodes Inc. Vishay-Dale	MOSFET, N-CH, 60 V, 0.17 A, SOT-23	SOT-23 0603
	4	10 TO		Vishay-Dale Vishay-Dale	RES, 130 k, 5%, 0.1 W, 0603	0603
R2, R3, R5, R6 R4	1	23.7k	CRCW060310R0JNEA CRCW060323K7FKEA	Vishay-Dale Vishay-Dale	RES, 10, 5%, 0.1 W, 0603 RES, 23.7 k, 1%, 0.1 W, 0603	0603
R8	1	1.0	CRCW060323R7FREA	Vishay-Dale Vishay-Dale	RES, 1.0, 5%, 0.1 W, 0603	0603
R9	1	20k				0603
R10	1	3.3k	CRCW060320K0JNEA CRCW06033K30JNEA	Vishay-Dale Vishay-Dale	RES, 20 k, 5%, 0.1 W, 0603 RES, 3.3 k, 5%, 0.1 W, 0603	0603
R11, R21	2	49.9k	CRCW06033K305NEA	Vishay-Dale Vishay-Dale	RES, 49.9 k, 1%, 0.1 W, 0603	0603
R12	1	64.9k	CRCW060364K9FKEA	Vishay-Dale Vishay-Dale	RES, 64.9 k, 1%, 0.1 W, 0603	0603
R13, R15	2	100	CRCW060304N9FKEA	Vishay-Dale Vishay-Dale	RES, 100, 1%, 0.1 W, 0603	0603
R14	1	100k	CRCW0603100KJNEA	Vishay-Dale Vishay-Dale	RES, 100 k, 5%, 0.1 W, 0603	0603
R16, R17, RH1,	6	0	CRCW0603100KJNEA	Vishay-Dale Vishay-Dale	RES, 0 ohm, 5%, 0.1W, 0603	0603
RH2, RL1, RL2	Ů			•		
R18	1	47	CRCW060347R0JNEA	Vishay-Dale	RES, 47, 5%, 0.1 W, 0603	0603
R19, R20	2	4.99k	CRCW06034K99FKEA	Vishay-Dale	RES, 4.99 k, 1%, 0.1 W, 0603	0603
R22, R23	2	6.65k	CRCW06036K65FKEA	Vishay-Dale	RES, 6.65 k, 1%, 0.1 W, 0603	0603
R24	1	9.53k	CRCW06039K53FKEA	Vishay-Dale	RES, 9.53 k, 1%, 0.1 W, 0603	0603
RS1	1	0.012	CSR1206FK12L0	Stackpole Electronics Inc	RES, 0.012, 1%, 0.5 W, 1206	1206
RS2	1	0.012	ERJ-M1WSF12MU	Panasonic	RES, 0.012, 1%, 1 W, 2512	2512

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
TP1, TP2	2	Red	5000	Keystone	Test Point, TH, Miniature, Red	Keystone5000
TP3, TP4	2	Black	5001	Keystone	Test Point, TH, Miniature, Black	Keystone5001
TP5, TP6, TP7,	6	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature
TP8, TP10, TP11						Testpoint
TP9, TP12, TP13	3	Triple	1598-2	Keystone	Terminal, Turret, TH, Triple	Keystone1598-2
U1	1		LM5175PWP	Texas Instruments	42V Wide VIN 4-Switch Synchronous Buck-Boost Controller, PWP0028F	PWP0028F
U2	1		LM2936MX-3.3	Texas Instruments	Ultra-Low Quiescent Current LDO Voltage Regulator, 8-pin Narrow SOIC	M08A
C12, C18	0	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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